



## Initial Product/Process Change Notification

Document #: IPCN26981X

Issue Date: 17 Dec 2025

|                                                  |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                       |
|--------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>Title of Change:</b>                          | Wafer Fab and Test Site Change for UFET Planar Products – Addition of Bucheon, Korea and assembly BOM changes (mold compound and lead frame)                                                                                                                                                                                                                                                                                                                                                                                                                                                                          |
| <b>Proposed First Ship date:</b>                 | 01 Oct 2026 or earlier if approved by customer                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                        |
| <b>Contact Information:</b>                      | Contact your local onsemi Sales Office                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                |
| <b>PCN Samples Contact:</b>                      | Contact your local onsemi Sales Office.<br>Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.<br>Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.                                                                                                                                                                                                                                                                                                     |
| <b>Type of Notification:</b>                     | This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact |
| <b>Marking of Parts/ Traceability of Change:</b> | The changed material can be identified by lot code and date code                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                      |
| <b>Change Category:</b>                          | Test Change, Wafer Fab Change                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                         |
| <b>Change Sub-Category(s):</b>                   | Equipment Change, Manufacturing Site Addition                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                         |

### Sites Affected:

| onsemi Sites          | External Foundry/Subcon Sites |
|-----------------------|-------------------------------|
| onsemi Bucheon, Korea | None                          |

### Description and Purpose:

This is an Initial Change Notification to inform customers of the qualification of onsemi Bucheon, Korea facility as alternate wafer fab site for UFET Planar Technology.

FPCNs to be issued in July of 2026 with first ship date as referenced above from Bucheon fab. If your FPCN approval will extend beyond the proposed first ship date, provide unit requirements for the unchanged material to your onsemi sales representative no later than March 31, 2026 by NCNR PO (Last order date for unchanged material). These bridge quantities will be limited and will be considered on a first come, first serve basis. onsemi will work with customers to facilitate the approval of the FPCNs by providing early samples and matching electrical data upon request, prior to the final PCN notices in July of 2026 to reduce customers' need for additional unchanged material.

|                | Before Change Description | After Change Description |                                   |
|----------------|---------------------------|--------------------------|-----------------------------------|
| FAB Site       | Mountain Top, PA, USA     | Mountain Top, PA, USA    | Bucheon 6 inch                    |
| Backgrind Site | Mountain Top, PA, USA     | Mountain Top, PA, USA    | Bucheon 6 inch                    |
| Probe Site     | Mountain Top, PA, USA     | Bucheon, Korea           | Bucheon, Korea                    |
| Wafer size     | 8 inch                    | 8 inch                   | 6 inch                            |
| Mold Compound  | KCC KTMCS900GM            | KCC KTMCS900GM           | Sumitomo G700HF or<br>HYSOL GR710 |
| Lead frame     | POR                       | PMC90                    | PMC90                             |

There is no product marking change because of this change.



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### Qualification Plan:

**QV DEVICE NAME** : HUF75852G3

**RMS** : 98202

**PACKAGE** : TO-247

| Test                                    | Specification                | Condition                                                                    | Interval  |
|-----------------------------------------|------------------------------|------------------------------------------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                  | Tj = Max rate Tj for device, bias =100% of rated V (Not to exceed max rated) | 1,008 hrs |
| High Temperature Gate Bias              | JESD22-A108                  | Tj = Max rate Tj for device, Max Vgs                                         | 1,008 hrs |
| High Temperature Storage Life           | JESD22-A103                  | Ta =Max rate storage temp for device                                         | 1,008 hrs |
| Highly Accelerated Stress Test          | JESD22-A110                  | Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max          | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                  | Temp = 130C, RH=85%, ~ 18.8 psig                                             | 96 hrs    |
| Temp Cycling                            | JESD22-A104                  | Temp = -55°C to +150°C                                                       | 1,000 cyc |
| Intermittent Operating Life             | MIL STD750, M 1037, AEC Q101 | Ta=+25°C, deltaTj=100°C max, 5 min Ton=Toff                                  | 6,000 cyc |

**QV DEVICE NAME** : RFP70N06

**RMS** : 98204

**PACKAGE** : TO-220

| Test                                    | Specification | Condition                                                                    | Interval  |
|-----------------------------------------|---------------|------------------------------------------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108   | Tj = Max rate Tj for device, bias =100% of rated V (Not to exceed max rated) | 1,008 hrs |
| Highly Accelerated Stress Test          | JESD22-A110   | Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max          | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118   | Temp = 130C, RH=85%, ~ 18.8 psig                                             | 96 hrs    |
| Temp Cycling                            | JESD22-A104   | Temp = -55°C to +150°C                                                       | 1,000 cyc |

Estimated date for qualification completion: 30 April 2026



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### List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

| Current Part Number | New Part Number | Qualification Vehicle |
|---------------------|-----------------|-----------------------|
| HUF75321D3ST        | #NONE           | HUF75852G3            |
| RFD16N05SM9A        | #NONE           | HUF75852G3            |
| HUF75339P3          | #NONE           | HUF75852G3            |
| HUF75344G3          | #NONE           | HUF75852G3            |
| HUF75344P3          | #NONE           | HUF75852G3            |
| HUF75345P3          | #NONE           | HUF75852G3            |
| HUF76407D3ST        | #NONE           | HUF75852G3            |
| HUF76423P3          | #NONE           | HUF75852G3            |
| HUF76439S3ST        | #NONE           | HUF75852G3            |
| RFD16N06LESM9A      | #NONE           | HUF75852G3            |
| RFD16N05LSM9A       | #NONE           | HUF75852G3            |
| RFD14N05LSM9A       | #NONE           | HUF75852G3            |
| RFD14N05LSM         | #NONE           | HUF75852G3            |
| RFD12N06RLESM9A     | #NONE           | HUF75852G3            |
| RFD3055LESM9A       | #NONE           | HUF75852G3            |
| HUF76429S3ST        | #NONE           | HUF75852G3            |
| RFP70N06            | #NONE           | HUF75852G3            |
| RFP50N06            | #NONE           | HUF75852G3            |
| RFD14N05SM9A        | #NONE           | HUF75852G3            |
| HUF75542P3          | #NONE           | HUF75852G3            |
| HUF75545P3          | #NONE           | HUF75852G3            |
| HUF75545S3ST        | #NONE           | HUF75852G3            |
| HUF75645P3          | #NONE           | HUF75852G3            |
| HUF75652G3          | #NONE           | HUF75852G3            |
| HUF76629D3ST        | #NONE           | HUF75852G3            |
| HUF76639S3ST        | #NONE           | HUF75852G3            |
| HUF75639G3          | #NONE           | HUF75852G3            |
| HUF75639P3          | #NONE           | HUF75852G3            |
| HUF75345S3ST        | #NONE           | HUF75852G3            |



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|              |       |            |
|--------------|-------|------------|
| HUF75345G3   | #NONE | HUF75852G3 |
| HUF75329D3ST | #NONE | HUF75852G3 |
| HUF75321P3   | #NONE | HUF75852G3 |
| BUZ11-NR4941 | #NONE | HUF75852G3 |
| HUF75639S3ST | #NONE | HUF75852G3 |
| RFP12N10L    | #NONE | HUF75852G3 |
| HUF75852G3   | #NONE | HUF75852G3 |